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PCB Number: TIDA-01585
PCB Rev: E1

PCB LOGO
PCB LOGO
PCB LOGO

CAUTION: READ USER GUIDE BEFORE USE

CAUTION: HOT SURFACE

CAUTION: HOT SURFACE

Assembly Note ZZ1
These assemblies are ESD sensitive, ESD precautions shall be observed.

Assembly Note ZZ2
These assemblies must be clean and free from flux and all contaminants. Use of no-clean flux is not acceptable.

Assembly Note ZZ3
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Assembly Note ZZ4
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